

CLAIMS

1. A polishing pad in which a polishing layer having a polishing region and a light-transmitting region, and a cushion
5 layer having a through hole are laminated via a double-sided adhesive sheet such that the light-transmitting region and the through hole are laid one upon another, wherein a transparent member is stuck on an adhesive layer of the double-sided adhesive sheet in the through hole.

10 2. The polishing pad according to claim 1, wherein the transparent member is a resin film subjected to an anti-reflection treatment and/or a light scattering treatment.

15 3. The polishing pad according to claim 1, wherein the transparent member is a resin film subjected to an anti-fouling treatment.

20 4. The polishing pad according to claim 1, wherein the transparent member is a resin film having a bandpass function.

5. A method for producing a semiconductor device, comprising the step of polishing a surface of a semiconductor wafer using the polishing pad according to claim 1.

Claims

[Claim 1]

A polishing pad in which a polishing layer having a polishing region and a light-transmitting region, and a cushion layer having a through hole are laminated via a double-sided adhesive sheet such that the light-transmitting region and the through hole are laid one upon another, wherein the double-sided adhesive sheet includes an adhesive layer on both surfaces of a transparent sheet, and a transparent member is stuck on an adhesive layer of the double-sided adhesive sheet in the through hole, and the transparent member is thinner than the cushion layer.

[Claim 2]

The polishing pad according to claim 1, wherein the transparent member is a resin film subjected to an anti-reflection treatment and/or a light scattering treatment.

[Claim 3]

The polishing pad according to claim 1 or 2, wherein the transparent member is a resin film subjected to an anti-fouling treatment.

[Claim 4]

The polishing pad according to any one of claims 1 to 3, wherein the transparent member is a resin film having a bandpass function.

[Claim 5]

A method for producing a semiconductor device, comprising the step of polishing a surface of a semiconductor wafer using the polishing pad according to any one of claims 1 to 4.